

绝缘胶 汉高乐泰Ablestik 2035SC红胶 摄像头模组绝缘胶

产品名称	绝缘胶 汉高乐泰Ablestik 2035SC红胶 摄像头模组绝缘胶
公司名称	东莞市石碣林茂电子材料销售部
价格	面议
规格参数	分类:环氧树脂 品牌:汉高ABLESTICK 型号:2035SC
公司地址	广东省东莞市石碣镇崇焕东路
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产品详情

product descriptionablebond 2035sc provides the following productcharacteristics:technology proprietary hybrid chemistryappearance redcure heat cureproduct benefits • non-conductive • single component • fast cure • low cure temperature • low stressapplication die attachph 3.7filler type silicaablebond 2035sc nonconductive die attach adhesive hasbeen formulated for use in high throughput die attachapplications. this material is designed to minimize stress andresulting warpage between dissimilar surfaces.typical properties of uncured materialhixotropic index (0.5/5 rpm) 4.2viscosity, brookfield cp51, 25 ° c, mpa · s (cp):speed 5 rpm 11,000work life @ 25 ° c, hours 24shelf life @ -40 ° c (from date of manufacture), year 1typical curing performancecure schedule90 seconds @ 110 ° calternative cure schedule60 seconds @ 120 ° c or 10 seconds @ 150 ° cthe above cure profiles are guideline recommendations. cureconditions (time and temperature) may vary based on customers'experience and their application requirements, as well as customercuring equipment, oven loading and actual oven temperatures.typical properties of cured materialphysical properties:coefficient of thermal expansion :below tg, ppm/ ° c 54above tg, ppm/ ° c 128glass transition temperature (tg) by tma, ° c 120thermal conductivity, w/mk 0.35tensile modulus, dmta :@ -65 ° c n/mm² 3,700(psi) (540,000)@ 25 ° c n/mm² 2,500(psi) (360,000)@ 150 ° c n/mm² 70(psi) (11,000)@ 250 ° c n/mm² 68(psi) (10,000)extractable ionic content, ppm:chloride (cl-) <30sodium (na+) <50potassium (k+) <20water extract conductivity, μ mhos/cm 75weight loss @ 300 ° c, % 2.51typical performance of cured materialdie shear strength:2 x 2 mm die, kg-f,die on substrate: @25 ° cau die on au pbga 11si die on ag leadframe 13si die on pd leadframe 12si die on pbga-fr4 12die shear strength vs temperature, kg-f:3 x 3 mm si die, kg-f,substrate @25 ° c @150 ° c @200 ° cpbga-fr4 25 7.0 4.0chip warpage vs chip size:0.38 mm thick si die on diff substrates @ 25 ° c, μ mchip size: warpage:12.7 x 12.7 mm 34general informationfor safe handling information on this product, consult thematerial safety data sheet, (msds).thawing:1. allow container to reach room temperature before use.2. after removing from the freezer, set the syringes to standvertically while thawing.3. do not open the container before contents reach 25 ° ctemperature. any moisture that collects on the thawedcontainer should be removed prior to opening thecontainer.tds ablebond 2035sc, july-20104. do not re-freeze. once thawed to -40 ° c, the adhesiveshould not be re-frozen.directions for use1. thawed adhesive should be immediately placed ondispense equipment for use.2. if the adhesive is transferred to a final dispensingreservoir, care must be exercised to avoid entrapment ofcontaminants and/or air into the adhesive.3. adhesive must be completely used within the product'srecommended work life.not for

product specificationsthe technical data contained herein are intended as referenceonly. please contact your local quality department forassistance and recommendations on specifications for thisproduct.storagestore product in the unopened container in a dry location.storage information may be indicated on the product containerlabeling.optimal storage: -40 ° c. storage below minus (-)40 ° c orgreater than minus (-)40 ° c can adversely affect productproperties.material removed from containers may be contaminated duringuse. do not return product to the original container. henkelcorporation cannot assume responsibility for product whichhas been contaminated or stored under conditions other thanthose previously indicated. if additional information is required,please contact your local technical service center orcustomer service representative.conversions(° c x 1.8) + 32 = ° fkv/mm x 25.4 = v/milmm / 25.4 = inchesn x 0.225 = lbn/mm x 5.71 = lb/inn/mm² x 145 = psimpa x 145 = psin · m x 8.851 = lb · inn · m x 0.738 = lb · ftn · mm x 0.1

本产品的分类是环氧树脂，品牌是汉高ABLESTICK，型号是2035SC，粘合材料是芯片与PCB